

INDIVIDUAL SPECIFICATION SHEET

Product Name: 0603 SMD Fuses

Part Number: F06T0.75

Revision: A



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Rev.	Effective Date	Changed Contents
A	2020-9-25	Update Specifications

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Description

F06T Series are the fuses set the industry standard for performance, reliability and quality. The solder-free design provides excellent on-off and temperature cycling characteristics during use and also makes our SMD fuses more heat and shock tolerant than typical subminiature fuses.

Electrical Characteristics				
Rated Current	1.0In	2.5In	3.0In	4.0In
750mA	4 hour minimum	0.1sec - 5.0 sec		

Features

- Compatible with reflow and wave solder
- Excellent environmental integrity
- One time positive disconnect
- Lead Free and Halogen free material

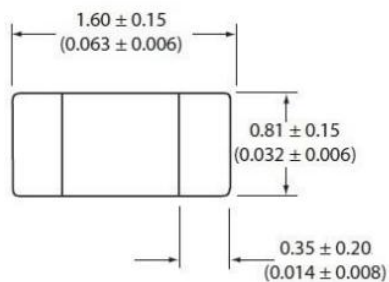
Specifications

Specification							
Part No.	Rated	Rated	Breaking Capacity (A) 1	Typical Cold. Resistance (mOhms) ²	Typical Voltage Drop (mV)	Typical Pre-Arcing I ² t (A ² Sec) ³	Alpha Mark
	Voltage	Current (A)					
	DC						
06 110.0.75	32V	0.75	50A	400	450	0.02	G

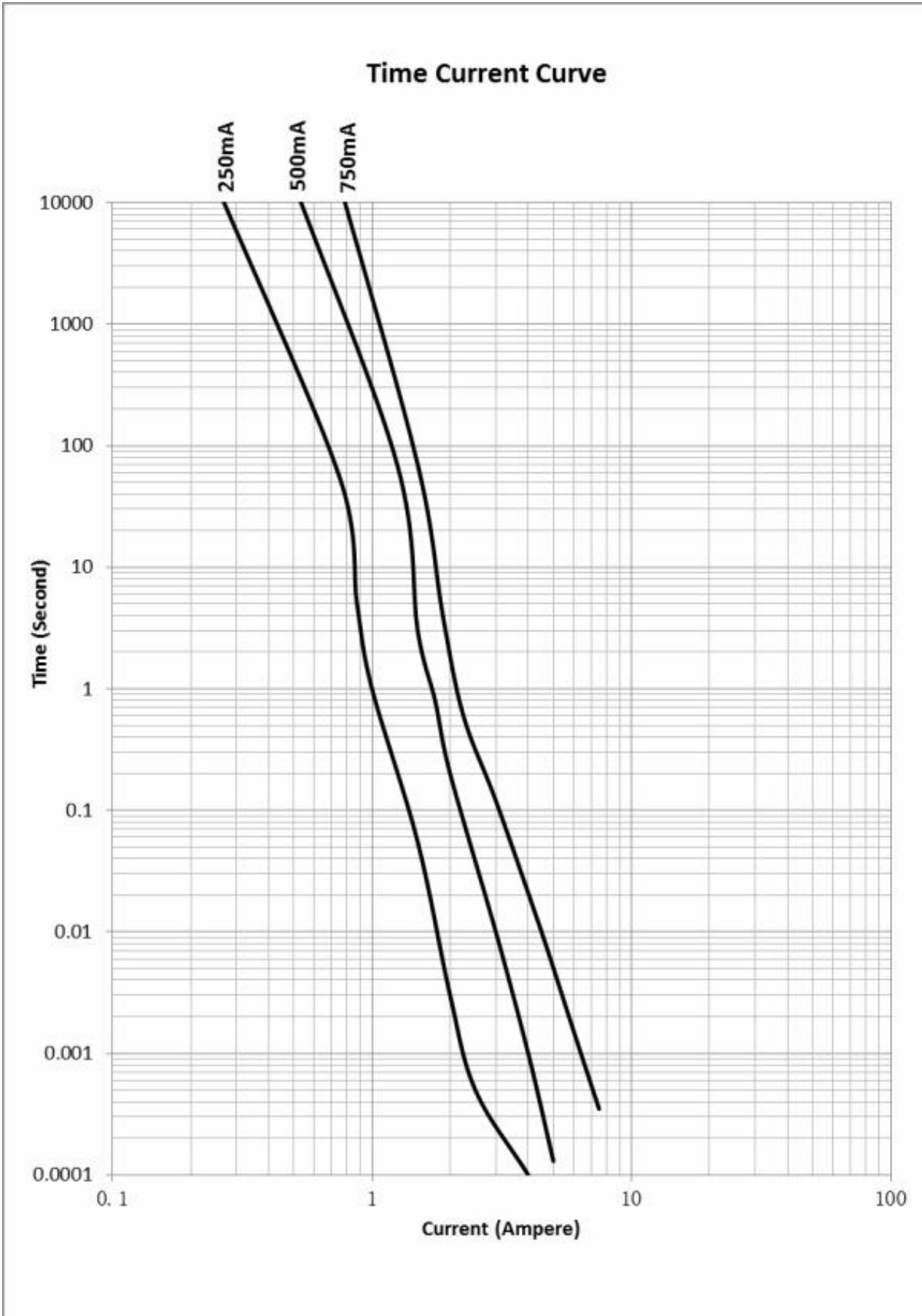
1. DC Interrupting Rating (Measured at rated voltage, time constant of less than 50 microseconds, battery source)
2. DC Cold Resistance are measured at <10% of rated current in ambient temperature of 25degrees
3. Typical Pre-arcing I²t are measured at 10In Current

Dimension

Drawing
(Unit: mm/inch)

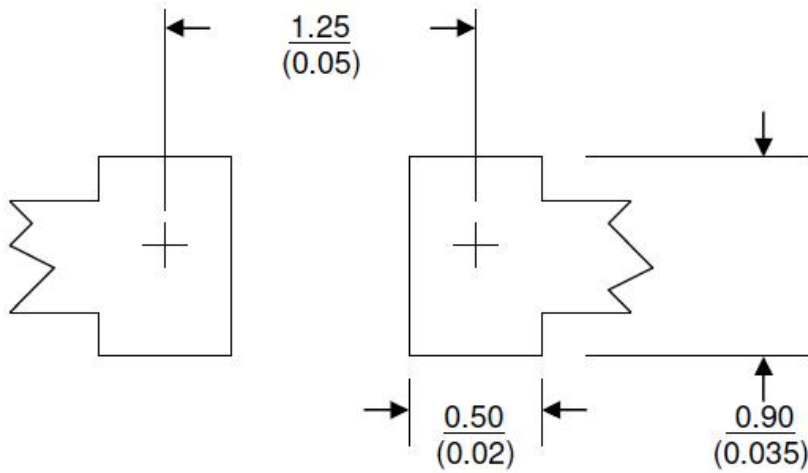


not to scale



***250mA 产品为系统短路保护应用设计，最小保护电流 4.0 倍

Recommended land pattern

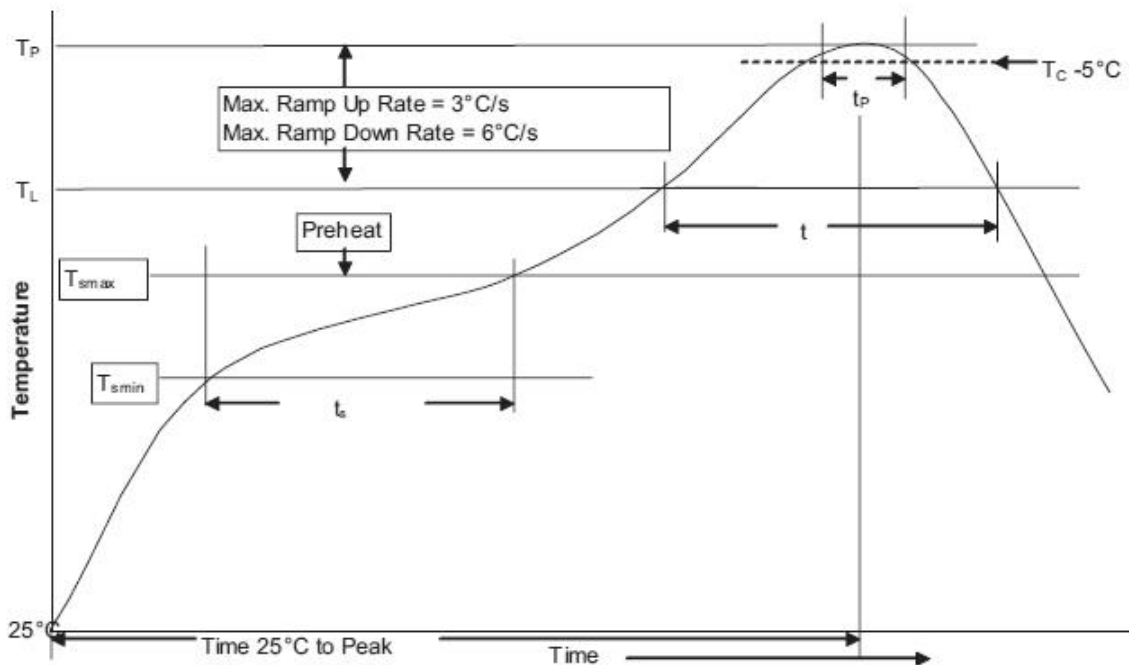


Unit: mm/inches

Soldering method

- Wave solder
 - Reservoir temperature: 260°C
 - Time in reservoir: 10 seconds maximum
- Infrared reflow
 - Temperature: 260°C
 - Time: 30 seconds maximum

Solder reflow profile



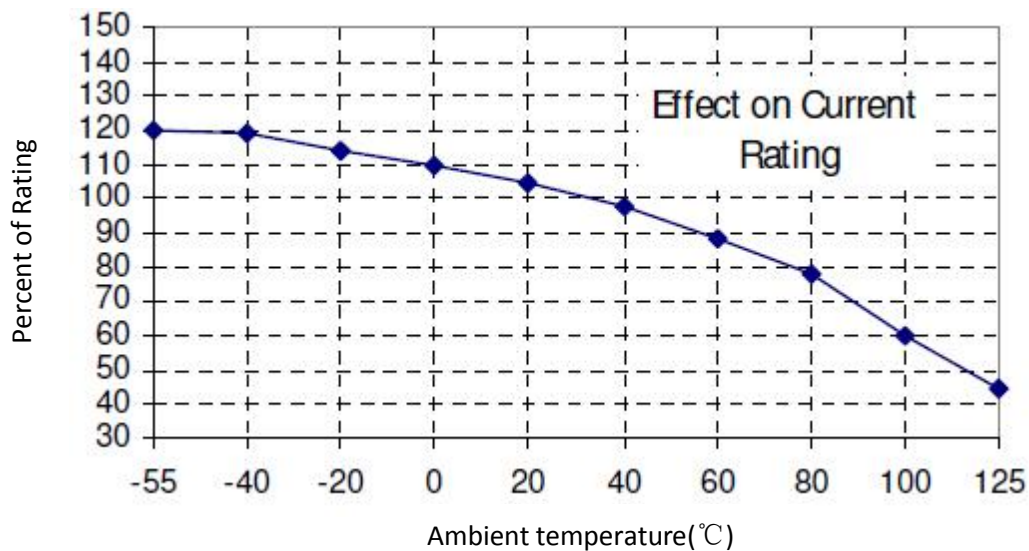
Profile Feature		Lead(Pb) free solder
Preheat and soak	• Temperature min.(T _{smin})	150°C
	• Temperature max. (T _{smax})	200°C

• Time (T_{smin} to T_{smax}) (t_s)	60 - 120 Seconds
Average ramp up rate T_{smax} to T_p	3°C / Second Max.
Liquidous temperature (T_L) Time at liquidous (t_L)	217°C 60 - 150 Seconds
Peak package body temperature (T_P)	260°C
Time (t_P) within 5°C of the specified classification temperature (T_C)	30 Seconds
Average ramp-down rate (T_P to T_{smax})	6°C / Second Max.
Time (25°C to Peak Temperature)	8 Minutes Max.

Temperature Derating Curve

Normal ambient temperature: 23+/-3°C

Operating temperature: -55 ~ 125°C, with proper correction factor applied



Package

5000 fuses on 8mm tape-and-reel on a 7 inch (178mm) reel per EIA Standard 481.

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